Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: P9A 20 VQFN 5.0x3.2x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Paris Cubatana	CAC Normalism	"Contained In" Sub-Component	% Total Weight			21.04	(mg) Total	Mold Compound	% ot Total Weight	51.94
Basic Substance	CAS Number	-		mg/part	ppm		law t		-	
Silica, fused Epoxy Resin	60676-86-0 Trade Secret	Mold Compound Mold Compound	46.746 2.519	18.932 1.020	467,460 25,191		Silica, fused Epoxy Resin	60676-86-0 Trade Secret	90.00 4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.519	1.020	25,191		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.156	0.063	1,558		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	39.643	16.055	396,426		Carbon Black	Total	100.00	
Iron	7439-89-6	Lead Frame	0.060	0.024	596	16.09	(mg) Total	Lead Frame	% of Total Weight	39.73
Phosphorous	7723-14-0	Lead Frame	0.016	0.006	159	10.09	Copper	7440-50-8	99.78	39.13
Zinc (Metal)	7440-66-6	Lead Frame	0.010	0.005	119		Iron	7439-89-6	0.15	
Silver	7440-22-4	Die Attach	0.932	0.377	9,317		Phosphorous	7723-14-0	0.04	
Acrylic Resin	Trade secret	Die Attach	0.169	0.069	1.694		Zinc (Metal)	7440-66-6	0.03	
Epoxy Resin	Trade secret	Die Attach	0.109	0.044	1.089			Total	100.00	
Silicon	7440-21-3	Chip (Die)	5.210	2.110	52,100	0.49	(mg) Total	Die Attach	% of Total Weight	1.21
Gold	7440-57-5	Wire Bond	0.650	0.263	6,500	00	Silver	7440-22-4	77.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.187	0.481	11.872		Acrylic Resin	Trade secret	14.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.045	0.018	455		Epoxy Resin	Trade secret	9.00	
Gold	7440-57-5	Plating on external leads (pins)	0.027	0.011	273			Total	100.00	
		TOTALS:	100.000	40.500	1.000.000	2.11	Total (mg)	Chip (Die)	% of Total Weight	5.21
	0.0405				.,,		10101 (119)	· · · · · · · · · · · · · · · · · · ·	,,	
niconductor device and its homogenous mate		g Total Mass th EU Directives: 2002/95/EC (27 January 2003) &	Directive 2011	/65/EU (08 Ju	ne 2011)		Doped Silicon	7440-21-3 Total	100.00 100.00	
5/863/EU (31 March 2015) and 2002/53/EC (En	erials comply wi nd-of-Life Vehicle	th EU Directives: 2002/95/EC (27 January 2003) &		,	ne 2011)	0.26	Doped Silicon (mg) Total			0.65
i/863/EU (31 March 2015) and 2002/53/EC (En nce with the above EU Directives has been v nical substance is absent from the list above p Technology Incorporated's knowledge and	erials comply with ad-of-Life Vehicle erified via intern the chemical su belief as of the	th EU Directives: 2002/95/EC (27 January 2003) & es (ELV) without exemption (zero)	analytical test d emiconductor do to believe that	ata. evice and, to tl the unavoidab	he best of	0.26		Total Wire Bond 7440-57-5	100.00 % of Total Weight 100.00	0.65
i/863/EU (31 March 2015) and 2002/53/EC (Ennce with the above EU Directives has been volical substance is absent from the list above p Technology Incorporated's knowledge and ation of the chemical substance, if any, is no	erials comply wind-of-Life Vehicle erified via intern the chemical substitution of the other the cother than the companion than the cother tha	th EU Directives: 2002/95/EC (27 January 2003) & s (ELV) without exemption (zero) al design controls, supplier declarations, and /or a distance is NOT an intentional ingredient in the sedate of this document, there is no credible reason shold of regulatory concern for any regulatory soly standard for plastics. You can access the UL iQ	analytical test d emiconductor do to believe that heme world-wic	ata. evice and, to the the unavoidable.	he best of ble impurity	0.26	(mg) Total	Total Wire Bond	100.00 % of Total Weight	0.65
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